

### Description

These dual N Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

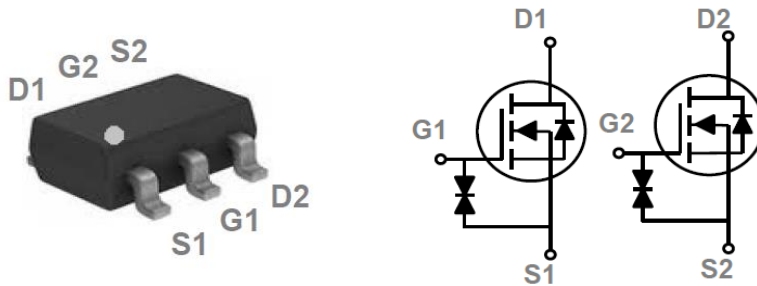
### Features

- ◆ 20V/0.8A,  $R_{DS(ON)} = 300\text{m}\Omega @ V_{GS} = 4.5\text{V}$
- ◆ Suit for 1.5V Gate Drive Applications
- ◆ Fast switching
- ◆ G-S ESD protection diode embedded
- ◆ SOT-363 package design

### Applications

- ◆ Networking
- ◆ Notebook
- ◆ Load Switch
- ◆ Hand - held Instruments

### SOT-363 Dual Pin Configuration



### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current	$I_D$	$T_C = 25^\circ\text{C}$	0.8
		$T_C = 100^\circ\text{C}$	0.51
Pulsed Drain Current	$I_{DM}$	3.2	A
Power Dissipation	$P_D$	$T_A = 25^\circ\text{C}$	275
		Derate above $25^\circ\text{C}$	2.2
Operating junction temperature range	$T_J$	- 55 to 150	$^\circ\text{C}$
Storage temperature range	$T_{STG}$	- 55 to 150	$^\circ\text{C}$

### Thermal Resistance Ratings

Parameter	Symbol	Maximum	Unit
Junction-to-Ambient	$R_{\theta JA}$	450	$^\circ\text{C}/\text{W}$



Ordering Information

Device	Package	REMARK
ECDEV2220Z	SOT-363	3000 pcs / Reel

Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250μA	0.3	0.6	1	V
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ± 6 V	-	-	±20	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V T <sub>J</sub> = 25 °C	-	-	1	μA
		V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125 °C	-	-	10	
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A	-	200	300	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 0.4A	-	235	400	
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 0.2A	-	295	550	
		V <sub>GS</sub> = 1.5V, I <sub>D</sub> = 0.1A	-	365	800	
		V <sub>GS</sub> = 1.2V, I <sub>D</sub> = 0.1A	-	600	1500	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 0.2A, V <sub>GS</sub> = 0V	-	-	1	V
<b>Dynamic Parameters</b>						
Input Cap.	C <sub>iss</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, F = 1MHz	-	38.2	75	pF
Output Cap.	C <sub>oss</sub>		-	14.4	28	
Reverse Transfer Cap.	C <sub>rss</sub>		-	6	12	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A	-	1	2	nC
Gate-Source Charge	Q <sub>gs</sub>		-	0.26	0.5	
Gate-Drain Charge	Q <sub>gd</sub>		-	0.2	0.4	
Turn-On Time	T <sub>D(ON)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.5A, V <sub>GS</sub> = 4.5V, R <sub>G</sub> = 10Ω	-	5	10	nS
	t <sub>r</sub>		-	3.5	7	
Turn-Off Time	T <sub>D(OFF)</sub>		-	14	28	
	t <sub>f</sub>		-	6	12	

Typical Characteristics

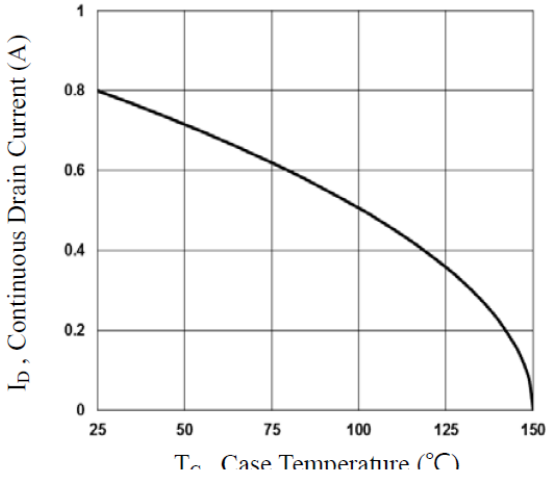


Fig.1 Continuous Drain Current vs.  $T_c$

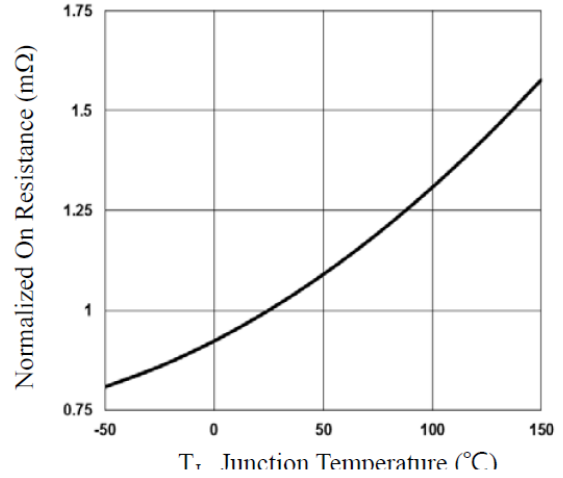


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$

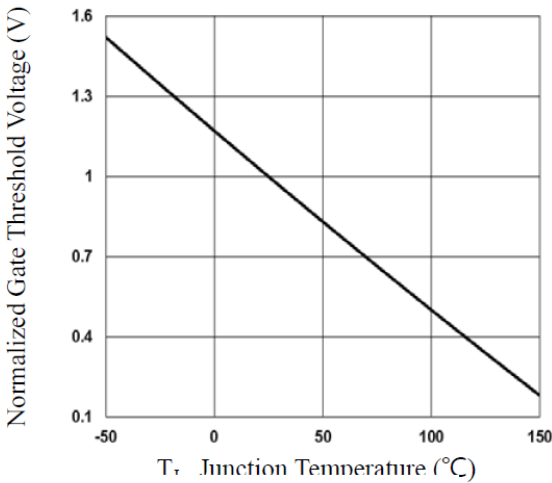


Fig.3 Normalized  $V_{th}$  vs.  $T_j$

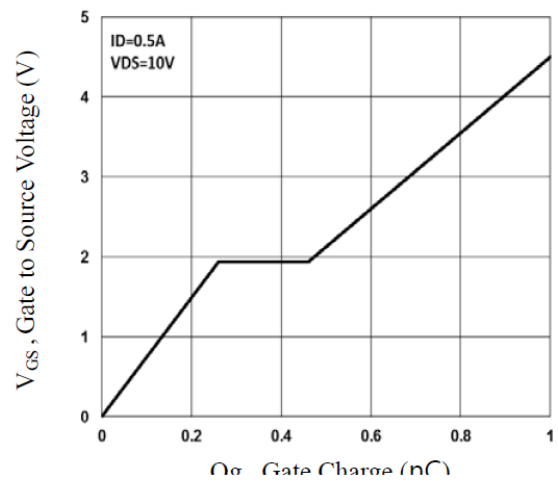


Fig.4 Gate Charge Waveform

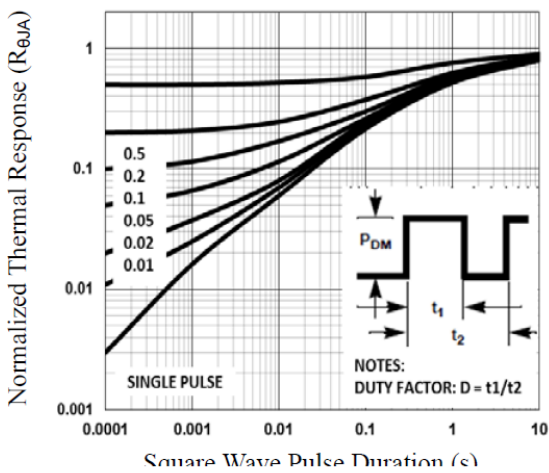


Fig.5 Normalized Transient Impedance

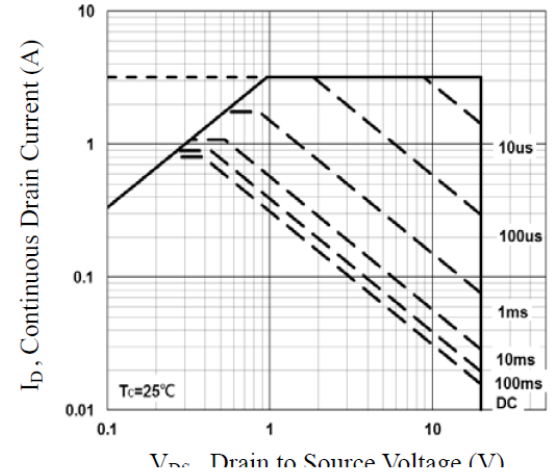
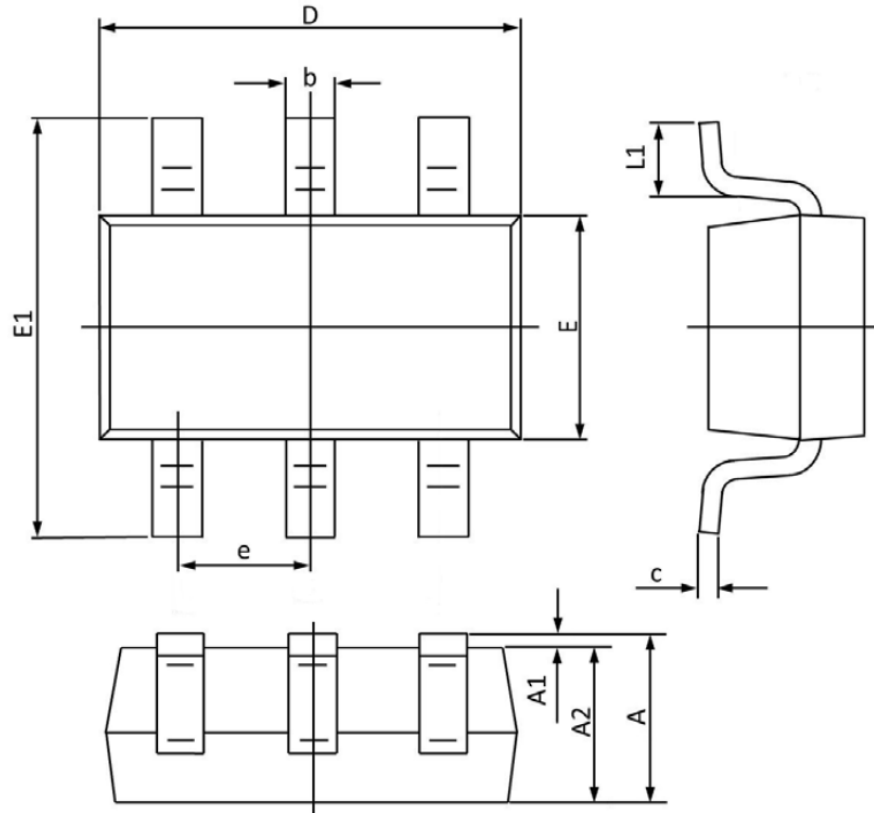


Fig.6 Maximum Safe Operation Area

**Physical Dimensions**

6Pin surface Mount SOT-363



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
A1	0.100	0.000	0.004	0.000
A2	1.000	0.800	0.039	0.031
b	0.330	0.100	0.013	0.004
c	0.250	0.100	0.010	0.004
D	2.200	1.800	0.087	0.071
E	1.350	1.150	0.053	0.045
E1	2.400	1.800	0.094	0.071
e	0.65BSC		0.026BSC	
L1	0.350	0.100	0.014	0.004